
MEC

PRODUCT SPECIFICATION

QUARTZ CRYSTAL

FREQUENCY COMPONENTS

| | |
|-------------------|--------------------------|
| PRODUCT TYPE | : SMD-1 €32 |
| NOMINAL FREQUENCY | : F1 €€€MHZ |
| PART NO | : SMD1 €3204SA-F1 M1 20F |
| REVISION | : A |

PRODUCT DESCRIPTION

Standard atmospheric conditions

Unless otherwise specified. The standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature $25\pm 2^{\circ}\text{C}$
Relative humidity $40\%\sim 70\%$

If there is no doubt the results, measurement shall be made within the following limits:

Ambient temperature $25\pm 2^{\circ}\text{C}$
Relative humidity : $40\%\sim 70\%$

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

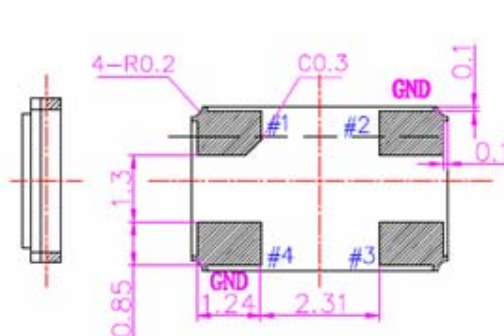
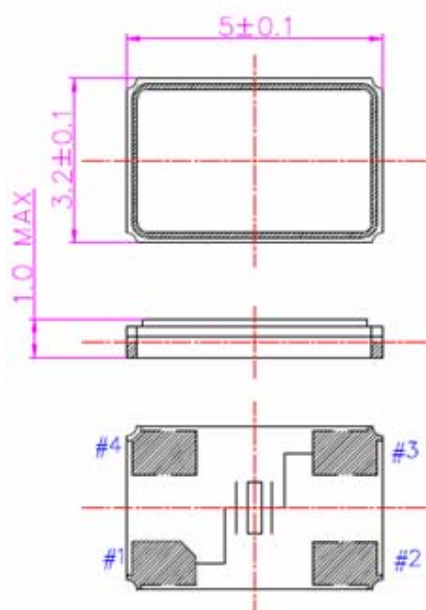
Crystal cutting type

The crystal is using AT CUT (thickness shear mode)

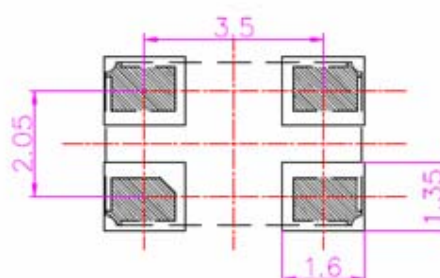
ELECTRICAL SPECIFICATIONS

| | Parameters | Symbol | Electrical Spec. | UNITS | Notes |
|----|--|--------|-------------------------------|--------------------|--|
| 1 | Nominal Frequency | FL | 16.000000 | MHz | - |
| 2 | Oscillation Mode | - | Fund | - | - |
| 3 | Load Capacitance | CL | 16.0 | p F | - |
| 4 | Frequency Tolerance | - | ± 20 | ppm | at $25\pm 2^{\circ}\text{C}$ |
| 5 | Operating Temperature | - | $-20\sim +70^{\circ}\text{C}$ | $^{\circ}\text{C}$ | - |
| 6 | Frequency Stability (reference 25°C) | - | ± 10 | ppm | $-20\sim +70^{\circ}\text{C}$ |
| 7 | Drive Level | DL | 100.0 | u W | - |
| 8 | Effective Resistance Rr | ESR | < 60.0 | ohm | - |
| 9 | Shunt Capaitance C0 | C0 | < 5.0 | p F | - |
| 10 | Insulation Resistance | IR | > 500 | M-ohm | at DC 100V |
| 11 | Aging | - | ± 5 | ppm | 1st Year |
| 12 | Reflow shift | - | ± 5 | ppm | at $265\pm 2^{\circ}\text{C} * 10\text{sec}$ |
| 13 | Storage Temperature Range | - | $-40\sim +85^{\circ}\text{C}$ | $^{\circ}\text{C}$ | - |
| 14 | ESD | - | HBM $> 2000\text{V}$ | $^{\circ}\text{C}$ | JESD22-A114-B |
| 15 | Others | - | - | - | - |
| | | | | | |
| | | | | | |
| | | | | | |

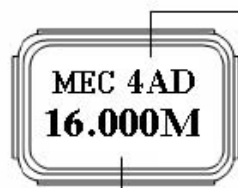
DIMENSIONS unit:mm



DIMENSIONS
(Unit: mm)



MARKING



Year code : 4=2014
Moth code : A=Jan

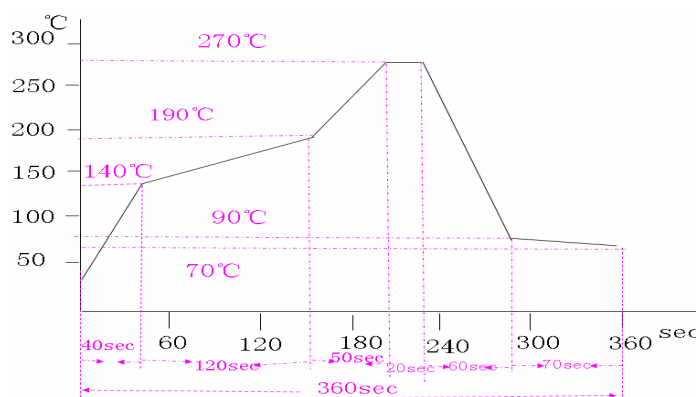
Frequency :
Ex: 16.000M=16MHz

| | | |
|---------|----------|----------|
| A - Jan | E - May | J - Sept |
| B - Feb | F - June | K - Oct |
| C - Mar | G - Jul | L - Nov |
| D - Apr | H - Aug | M - Dec |

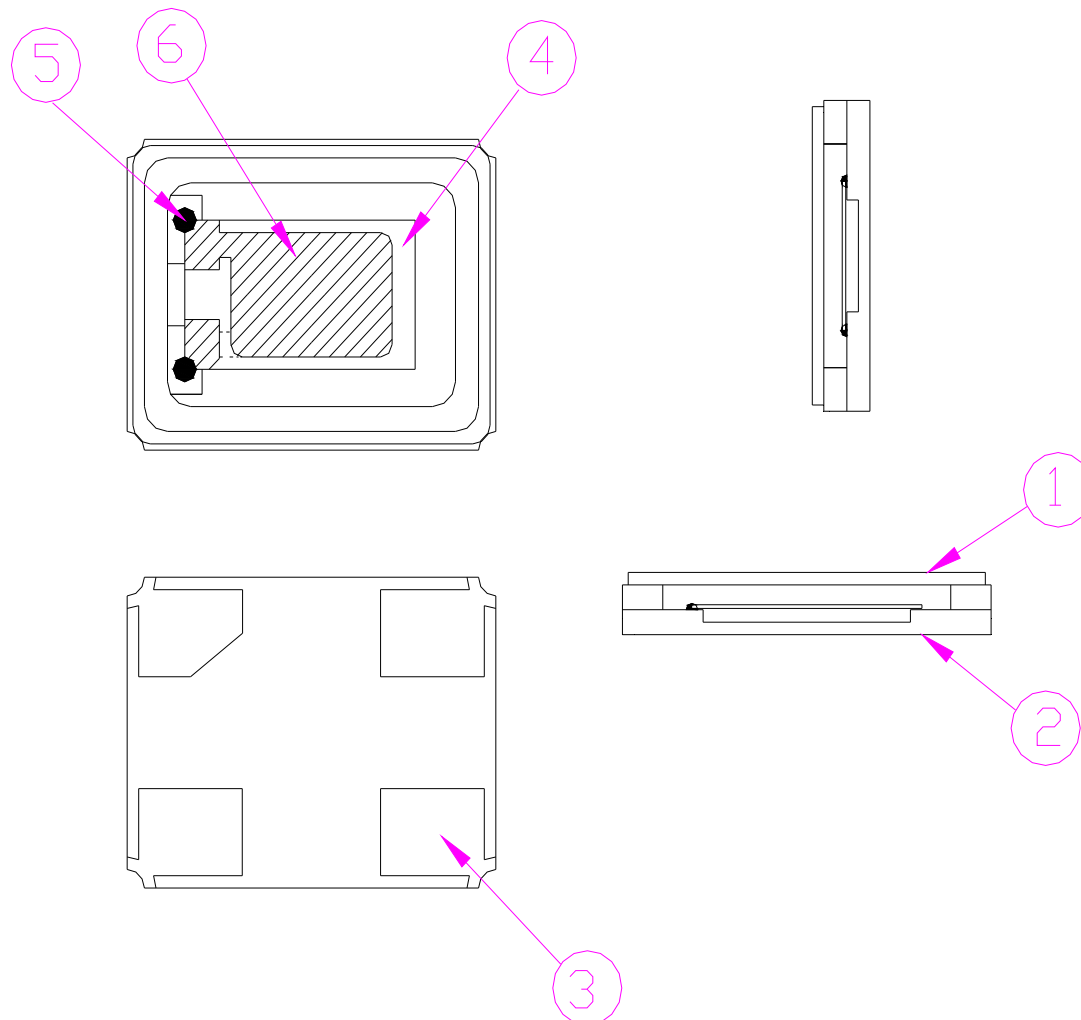
SUGGESTED REFLOW PROFILE

Total time : 360 sec. Max.

Solder melting point : 185 °C



STRUCTURE ILLUSTRATION



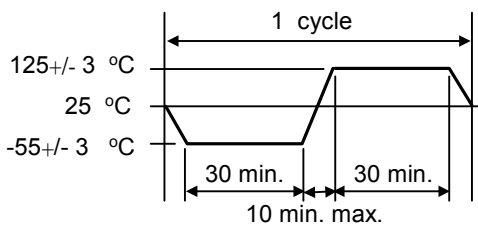
| NO | COMPONENTS | MATERIALS | QTY | FINISH/SPECIFICATIONS |
|----|---------------------|------------------------------------|-----|---|
| 1 | Cap(Lid) | Metal(Fe) | 1 | - |
| 2 | Base(Package) | Ceramic(Al_2O_3) | 1 | Alumina ceramics |
| 3 | Pad(Package) | Au | 4 | Tungsten metalize +Ni plating +Au plating |
| 4 | Crystal blank | SiO_2 | 1 | - |
| 5 | Conductive adhesive | Ag | 4 | Silicone resin |
| 6 | Electrode | Ag + Cr | 2 | - |

RELIABILITY SPECIFICATIONS

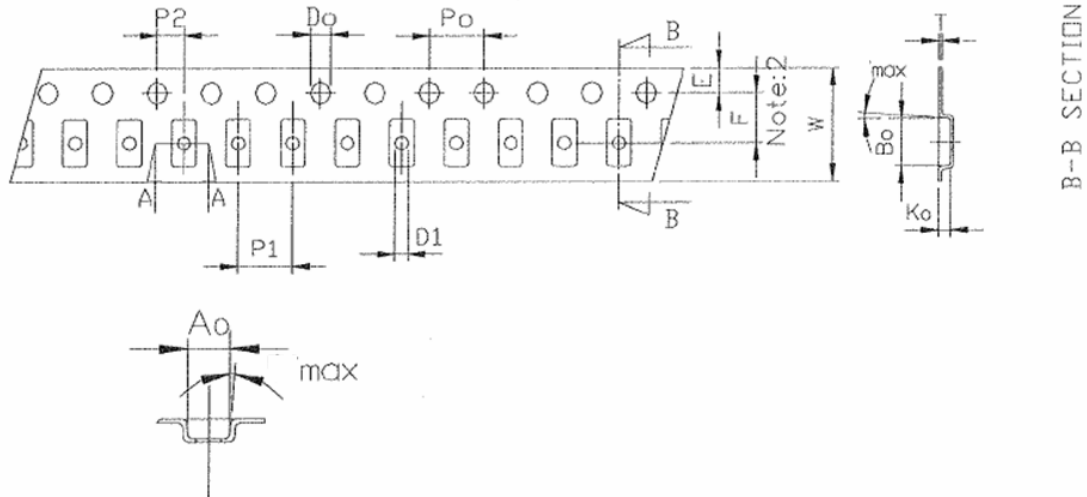
1.MECHANICAL ENDURANCE

| No. | Test Item | Test Methods | |
|-----|------------------------------|---|--------------|
| 1 | Drop Test | 150 cm height, fall freely onto stainless plate 3 times. | JIS C6701 |
| 2 | Shock Test | 150g/150cm Height, 3 times in the direction of $\pm x$, $\pm y$, $\pm z$ on concrete floor | IEC-68-02-27 |
| 3 | Mechanical Shock | Device are shocked to half sine wave (1000 G) three mutually pendicular axes each 3 times. 1.0m sec. duration time | MIL-STD-202F |
| 4 | Vibration | Frequency range 10 ~ 55 Hz Amplitude 1.52 mm Pendicular axes each test time 2 hours (x,y,z Axis) Total test time 6 hours | MIL-STD-883E |
| 5 | Gross Leak | Standard Sample For Automatic Gross Leak Detector Test Pressure 2kg/cm ² | MIL-STD-883E |
| 6 | Fine Leak | Helium Bombing 4.5kgf/cm ² for 2 hr | MIL-STD-883E |
| 7 | Solderability | Temperature 215 °C \pm 5 °C Immersing depth 0.5 mm minimum Immersion time 10 \pm 0.5 seconds Flux Rosin resin methyl alcohol solvent (1 : 4) | MIL-STD-883E |
| 8 | Resistance To Soldering Heat | Pre-heat temperature 125 °C Pre-heat time 60 ~ 120 sec. Test temperature 260 \pm 5 °C Test time 5 \pm 1 sec. | MIL-STD-202F |

2.ENVIRONMENTAL ENDURANCE

| No. | Test Item | Test Methods | |
|-----|-------------------------|---|--------------|
| 9 | High Temp. Storage | + 125 °C \pm 3 °C for 500 \pm 12 hours | MIL-STD-883E |
| 10 | Low Temp. Storage | - 40 °C \pm 3 °C for 500 \pm 12 hours | |
| 11 | Thermal Shock | Total 100 cycles of the following temperature cycle  | MIL-STD-883E |
| 12 | High Temp&Homidity | 85°C \pm 3°C, RH 85%,500Hrs | JIS C5023 |
| 13 | Pressure Cooker Storage | 120 \pm 3°C, RH100%, 2 bar, for 240 hours | JIS C6701 |

PACKING : (EIA-481-2)



| Dimension PKG Type | Unit : mm | | | | | | |
|-----------------------|-----------|---------|-----------|-----------|--------|----------|---------|
| | A0 | B0 | K0 | T | W | E | F |
| 5032(12mm) | 3.6±0.1 | 5.4±0.1 | 1.4±0.1 | 0.3±0.05 | 12±0.2 | 1.75±0.2 | 5.5±0.2 |
| | P1 | P2 | D1 | D0 | P0 | | |
| | 8±0.1 | 2±0.1 | 1.55±0.05 | 1.55±0.05 | 4±0.1 | | |

Standard Reel Quantity is 1,000 pcs per reel.


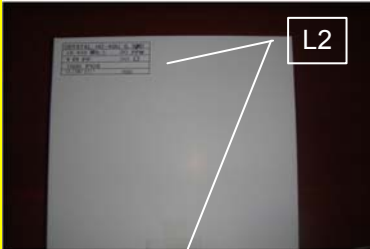


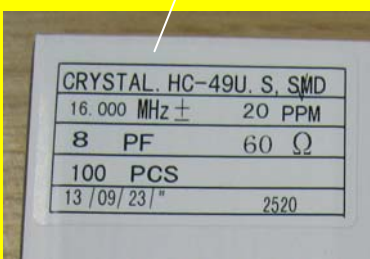

THE INSPECTION FOR TAPE TENSION

| ITEM | | Defect | Method |
|--------------|--|---|-------------------|
| Appearance | ALL | 1.The tape is not coincidence 2.The bubble | Visual inspection |
| Tape Tension | 8045、7050 6035-12mm 5032-12mm 3225-12mm | overstep 61±6g(55~67g) | Pull test |
| | 3225-8mm | overstep 40±5g(35~45g) | |
| | 2520-8mm | overstep 55±6g(49~61g) | |
| | 2016-8mm | overstep 34±6g(28~40g) | |
| | 1612-8mm | overstep 34±6g(28~40g) | |
| | 6035-16mm 5032-16mm | overstep 60±6g(54~66g) | |


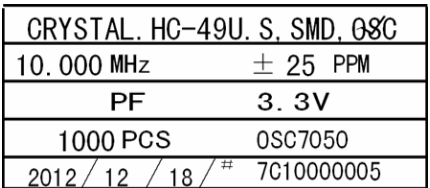
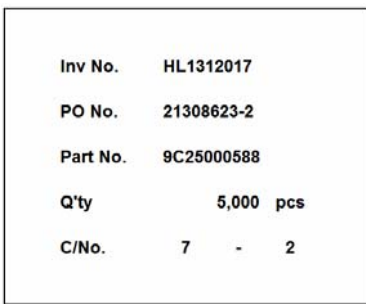
REMARK : NA

SMD PRODUCT PACKING STANDARD

Out-going packing instruction

| Reel Packing | Inner Packing | Carton |
|--|--|--|
| name: reel standard: diameter 18cm material: plastics | name: inner box standard: L19.0xW19.0xH2.5cm material: B corrugated paper | name: carton standard: L34.0xW22.0xH22.0cm material: AB corrugated paper(10 boxes enter) |
|  |  |  |
|  |  |  |

The label instruction

| Label Drawing | Mark | Name of Article | Spec. | Size | Printing |
|---|------|---|---|-----------|----------|
|  | L1 | 条码标签 Bar Code Label (Chintz Paper) | 1.Date Code 2.Lot No. 3.Part No. 4.Freq 5.Q'ty | 75x35mm | White |
|  | L2 | 机打标签 Printing Label (Printing Paper) | 1.Freq 2.Electrical Parameters 3.Q'ty 4.Part No. 5.Packing Date | 75x35mm | White |
|  | L3 | 运输标签(唛头) Shipping Mark (Printing Paper) | 1.inv No. 2.PO No. 3.Part No. 4.Q'ty 5.C/No. | 100x100mm | White |

Remark

Specifications on the label is for the use of templates with different product specifications may vary.

If customer specified requirements for labels packaging, please provide the operation pro

| Mobicon Holdings Limited 7/F., New Trend Centre, 704 Prince Edward Road East, San Po Kong, Kowloon, Hong Kong. Tel: (852) 2397 6628 / 2397 8218; Fax: (852) 2397 0339 / 2397 8187 http://www.mobicon.com E-mail: info@mobicon.com | | | MHL P/N: SMD503204SA-16M1620F | |
|---|----------------------------------|----------------------------------|---|-----------|
| | | | VER: A | PAGE: 8/9 |
| Range | Products | Packing Material | Test Method | |
| Banned Substances | Maximum concentration ppm(mg/kg) | Maximum concentration ppm(mg/kg) | | |
| 1.镉及镉化合物 Cadmium and cadmium compounds | 5 | 5 | ICP-AES as per EN1122, method B2001 or other acid digestion. | |
| 2.铅及铅化合物 Lead and lead compounds | 40 | 100 | ICP-AES after as per EPA 3050B or other acid digestion. | |
| 3.汞及汞化合物 Mercury and mercury compounds | 5 | 5 | ICP-AES after as per EPA 3052 or other acid digestion. | |
| 4.六价铬化合物 Hexavalent-Chromium VI (Cr+6) | 10 | 10 | As per US EPA 7196A and US EPA 3060A. | |
| 5.聚溴联苯 PBB Polybrominated biphenyls | 5 | 5 | With reference to USEPA 3540 or USEPA3550. Analysis was performed by LPLC/DAD, LC/MS or GC/MS. (prohibited by 2002/95/EC (RoHS),83/261/EEC, and76/769/EEC) | |
| 6.聚溴二苯醚 PBDE Polybrominated diphenyl ethers | 5 | 5 | With reference to USEPA3540or USEPA3550. Analysis was performed by HPLC/DAD LC/MS or GC/MS.(prohibited by 2002/95/EC(RoHS), 83/264/EEC, and 76/769/EEC) | |
| 7.多氯联苯 (PCB) Polychlorinated biphenyl | 5 | 5 | | |
| 8.多氯化萘 (PCN) Polychlorinated naphthalene | 5 | 5 | | |
| 9.氯代烷烃 (CP) Chlorinated paraffin | 5 | 5 | | |
| 10.其他有机氯化物 Other chlorinated organic compounds | 5 | 5 | | |
| 11.其他有机溴化合物 Other brominated organic compounds | 5 | 5 | | |
| 12.有机锡化合物 (三丁基锡化合物,三苯基锡化合物) Organic tin compounds (Tributyl tin category & Triphenyl tin category) | 5 | 5 | | |
| 13.石棉 Asbestos | 5 | 5 | | |
| 14.偶氮化合物 Azo compounds | 5 | 5 | | |
| 15.甲醛 Formaldehyde | 5 | 5 | | |
| 16.聚氯乙烯(PVC)以及聚氯乙烯混合物 Polyvinyl chloride (PVC) and PVC blends | No detect | No detect | | |
| 17.包装材料中重金属(汞、镉、六价铬、铅、PBB、PBDE)之总量 Heavy metals (mercury, cadmium, lead, Cr+6,PBB and PBDE) in packing | N/A | <100 | | |
| Lead Free Products are “Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of certain hazardous substances (RoHS) in electrical and electronic equipment” and Sony SS-00259 Compliant. | | | | |

MEC

REVIEW OF SPECIFICATIONS

- 1) When something get doubtful with this specifications, we shall jointly work to get an agreement.
- 2) This specification limits the quality of the components as a single unit. Please insure the component is thoroughly evaluated in your application circuit.
- 3) Please do not use this component in any application that deviates from its intended use as noted within the specification. It may cause any mishaps.
- 4) Please return one of this specification after your signature of acceptance. In case of no return within 3 months from submission date. This specification should be treated as accepted.

When using our products, the following precautions should be taken.

- (1) Safety designing of apparatus or a system allowing for failures of electronic components used in the system

In general, failures will occur in electronic components at a certain probability. MOBICON HOLDINGS LTD makes every effort to improve the quality and reliability of electronic component products. However, it is impossible to completely eliminate the probability of failures. Therefore, when using MOBICON HOLDINGS LTD electronic component products, systems should be carefully designed to ensure redundancy in the event of an accident which would result in injury or death, fire, or social damage, to ensure the prevention of the spread of fire, and the prevention of faulty operation.

- (2) Quality Level of various kinds of parts, and equipment in which the parts can be utilized
Electronic components have a standard quality level unless otherwise specified.
- (3) This specifications is subject to change without notice.
The contents of this specifications are based on data which is correct as of 2002, and they may be changed without notice. If our products are used for mass-production design, please enquire consult with a member of our company's sales staff by way of precaution.
- (4) Reprinting and copying of this specifications without prior written permission from MOBICON HOLDINGS LTD are not permitted.

- (5) Industrial Property Problems

In the event any problems associated with industrial property of a third party arising as a result of the use of our products. MOBICON HOLDINGS LTD assumes no responsibility for problems other than problems directly associated with the constitution and manufacturing method of the products.